

L Number	Hits	Search Text	DB	Time stamp
3	2	"200018353"	JPO; DERWENT	2003/09/15 12:50
4	69536	((substrate or board or carrier) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 12:51
5	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 12:52
6	11872	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 12:55
7	3108	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad)) and ((slit or gap or hole or space) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 13:57
8	3007	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad)) and ((solder or ball or bump) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 13:46
9	1795	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad)) and ((solder or ball or bump) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 13:45
10	583	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad)) and ((slit or gap or hole or space) with (air or escape or moisture or vent or bubbles))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 13:55
11	322	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad)) and ((slit or gap or hole or space) with (air or escape or moisture or vent or bubbles)) and (&ad<20000312)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 14:03
12	108	((substrate or board or carrier) with (land or pad)) and ((cavity or recess or via or trench) with (land or pad)) and ((slit or gap or hole or space) with (air or escape or moisture or vent or bubbles)) and (&ad<20000312) and ((solder or ball or bump or reflow) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 13:47
13	7	("4664962" "5315072" "5404044" "5406034" "5541368" "5689091" "5783865").PN.	USPAT	2003/09/15 13:53
14	2	5962922.URPN.	USPAT	2003/09/15 13:53
15	1002	(pad or land) with ((air or escape or moisture or vent or bubbles) and (reflow or solder or ball or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 13:57
16	326	((pad or land) with ((air or escape or moisture or vent or bubbles) and (reflow or solder or ball or bump))) and ((slit or gap or hole or space) with (land or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/15 14:00

17	219	((pad or land) with ((air or escape or moisture or vent or bubbles) and (reflow or solder or ball or bump))) and ((slit or gap or hole or space) with (land or pad))) and (@ad<20000312)	USPAT; US-PGPUB; EPO; JFO; DERWENT; IBM TDB	2003/09/15 14:03
18	3	6028366.URPN.	USPÄT	2003/09/15 14:05